

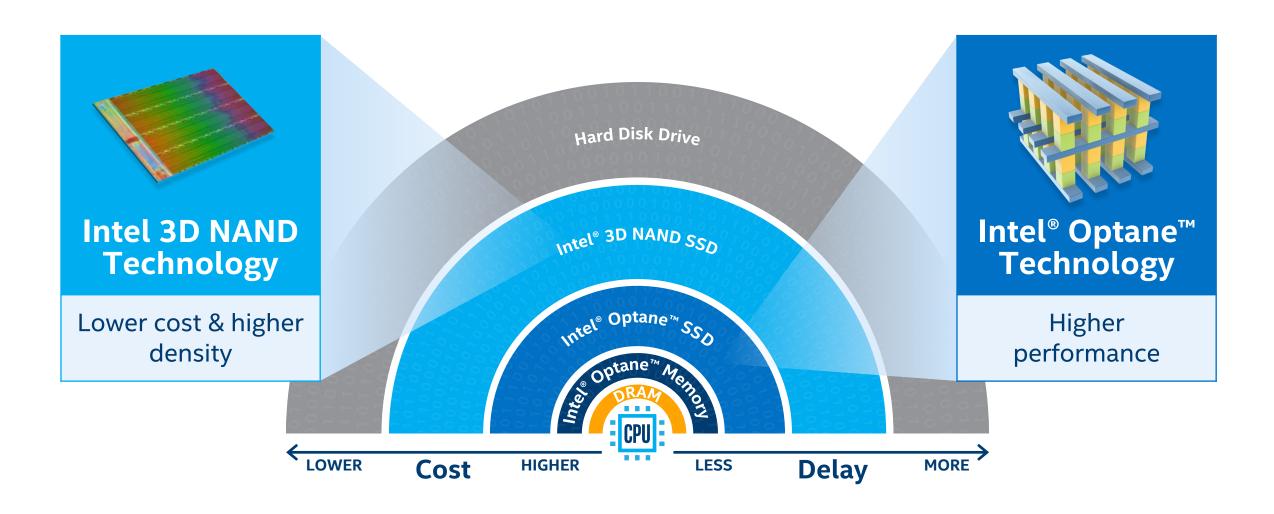
INTEL® SSD DATA CENTER EVOLUTION

March 2018

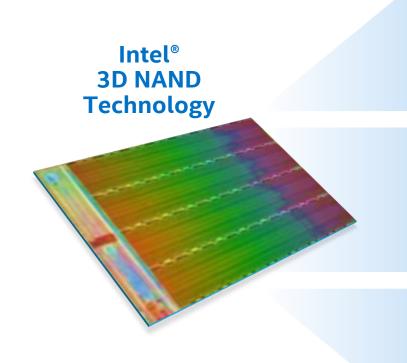


Intel Technology Innovations Fill the Memory and Storage Gap

Performance and Capacity for Every Need



Intel 3D NAND Leadership



Up to 20% Higher Areal Density¹ vs. Competition

Denser memory array

Intel floating gate cell has a smaller footprint¹

More efficient utilization

Intel CMOS under array

Accelerating Moore's Law into 3 Dimensions

Architected for capacity scaling leadership

Faster cadence generation to generation

Why Does This Matter?

The combination of performance, capacity and cost of Intel® 3D NAND SSDs will rapidly accelerate HDD replacement.

¹Comparing areal density of Intel measured data on 512GB Intel 3D NAND to representative competitors based on 2017 IEEE International Solid-State Circuits Conference papers citing Samsung Electronics and Western Digital/Toshiba die sizes for 64-stacked 3D NAND component.



Intel® 3D NAND SSDs

Transforming the economics of storage with trusted, breakthrough 3D NAND technology



- Architected for highest areal density¹
- Optimized for manufacturing efficiency



Built on a proven process

- Leader in flash cell technology evolution and scaling
- Accelerated development²
- First to high volume manufacturing with 64-Layer TLC³



Enabling disruptive opportunities

- Growing capacity faster than the market⁴
- Rapid portfolio expansion
- Space and power efficient capacities reduce TCO
- 1. Comparing areal density of Intel measured data on 512 GB Intel 3D NAND to representative competitors based on 2017 IEEE International Solid-State Circuits Conference papers citing Samsung Electronics and Western Digital/Toshiba die sizes for 64-stacked 3D NAND component.
- 2. Anand Tech '3D NAND Die Size Comparison' http://www.forward-insights 'QLC in the Datacenter', May 2017, http://www.forward-insights.com/reportslist.html
- 3. Intel® SSD 545s Series available on NewEgg® https://www.newegg.com/SSDs/Category/ID-119 June 27, 2017.
- 4. Based on Intel internal forecasting 2016-2017. Forecasts are Intel estimates, based upon expectations and available information and are subject to change without notice.



Intel® Optane™ Technology: 3D XPoint™ Memory Media

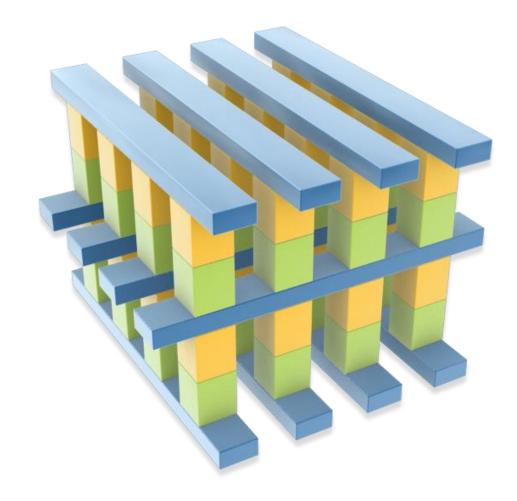
Cross Point Structure

Selectors allow dense packing and individual access to bits



Scalability

Memory layers can be stacked in a 3D manner



Breakthrough Material Advances

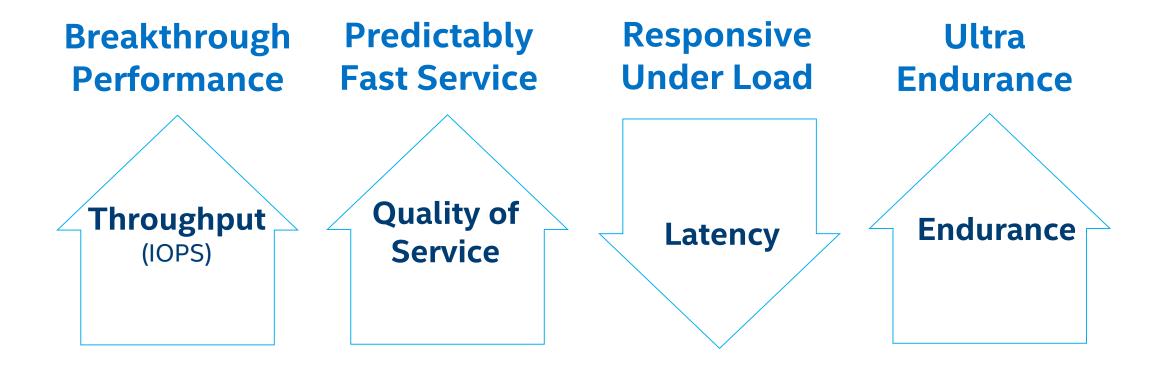
Compatible switch and memory cell materials



High Performance

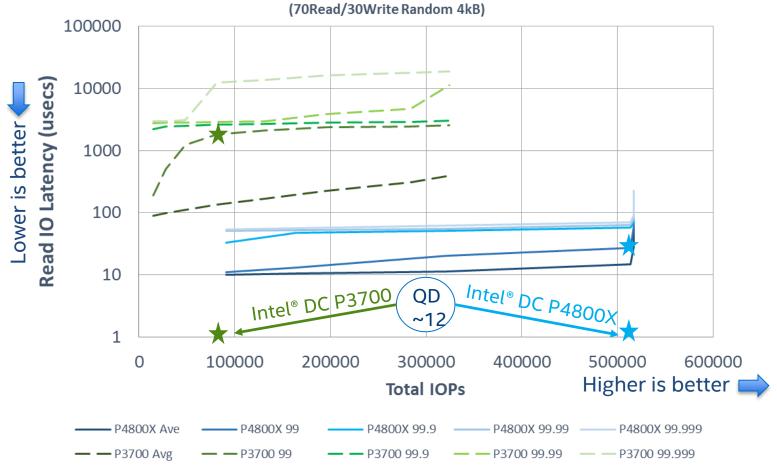
Cell and array architecture that can switch states much faster than NAND

Intel® Optane™ SSD DC P4800X



Storage Performance Characterization

Latency vs. Load¹: NAND SSD vs. Intel® Optane™ SSD (Intel® SSD DC P3700 vs. Intel® Optane™ SSD DC P4800X)



10x latency reduction

< 10usec latency²

100x QoS improvement

< 200usec 99.999th r/w²</p>

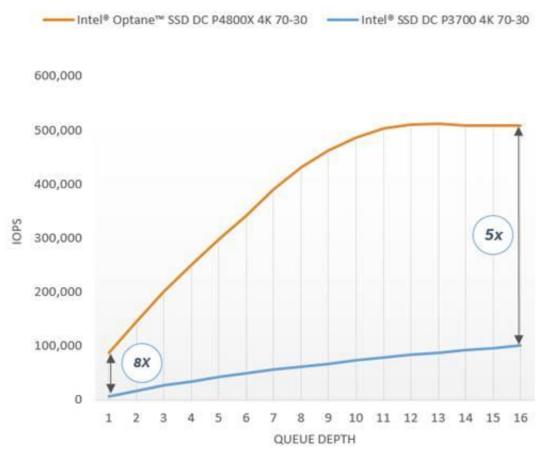


^{1.} Benchmark results were obtained prior to implementation of recent software patches and firmware updates intended to address exploits referred to as "Spectre" and "Meltdown." Implementation of these updates may make these results inapplicable to your device or system. Common Configuration - Intel 2U Server System, OS CentOS 7.2, kernel 3.10.0-327.el7.x86_64, CPU 2 x Intel® Xeon® E5-2699 v4 @ 2.20GHz (22 cores), RAM 396GB DDR @ 2133MHz. Configuration - Intel® Optane™ SSD DC P4800X 375GB and Intel® SSD DC P3700 1600GB. Performance - measured under 4K 70-30 workload at QD1-16 using fio-2.15. Tests document performance of components on a particular test, in specific systems. Differences in hardware, software, or configuration will affect actual performance.

Vs. NAND based SSD.

Breakthrough Performance

4K 70/30 RW Performance at Low Queue Depth







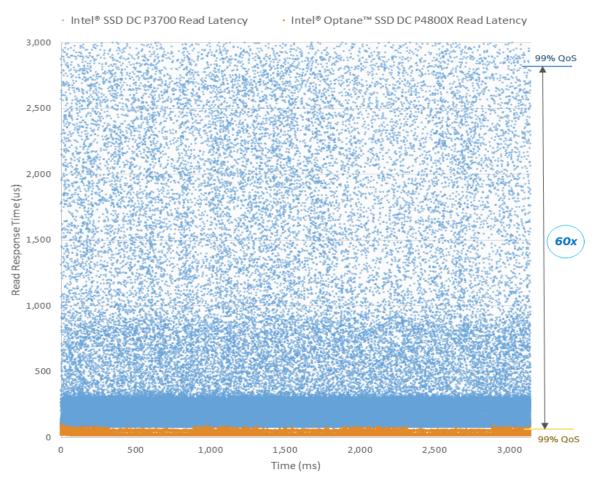


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Predictably Fast Service

Read QoS in Mixed Workload



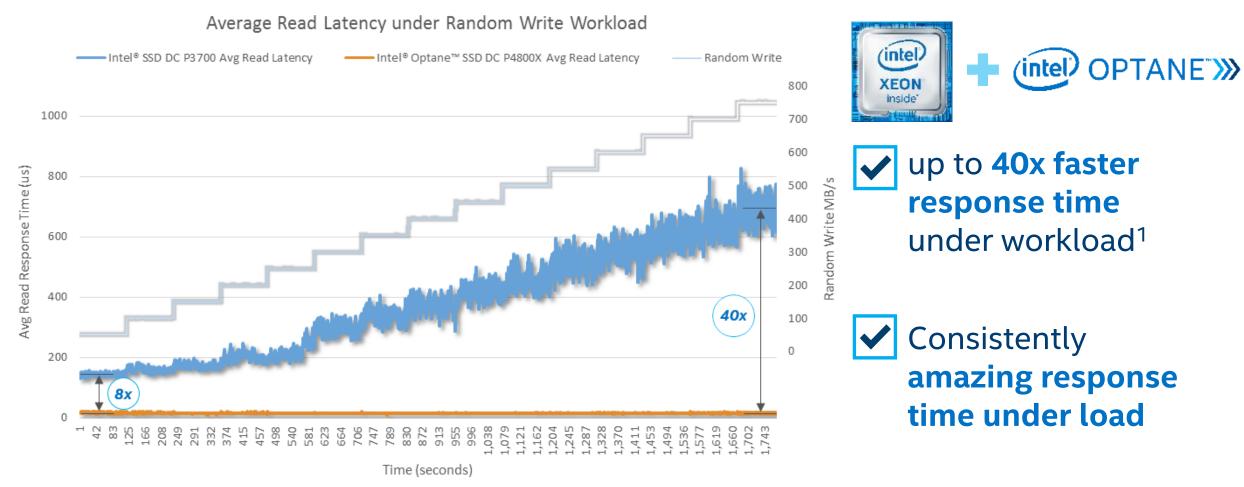






^{1.} Benchmark results were obtained prior to implementation of recent software patches and firmware updates intended to address exploits referred to as "Spectre" and "Meltdown." Implementation of these updates may make these results inapplicable to your device or system. Common Configuration – Intel 2U Server System, OS CentOS 7.2, kernel 3.10.0-327.el7.x86_64, CPU 2 x Intel® Xeon® E5-2699 v4 @ 2.20GHz (22 cores), RAM 396GB DDR @ 2133MHz. Configuration – Intel® Optane™ SSD DC P4800X 375GB and Intel® SSD DC P3700 1600GB. QoS – measures 99% QoS under 4K 70-30 workload at QD1 using fio-2.15. Tests document performance of components on a particular test, in specific systems. Differences in hardware, software, or configuration will affect actual performance.

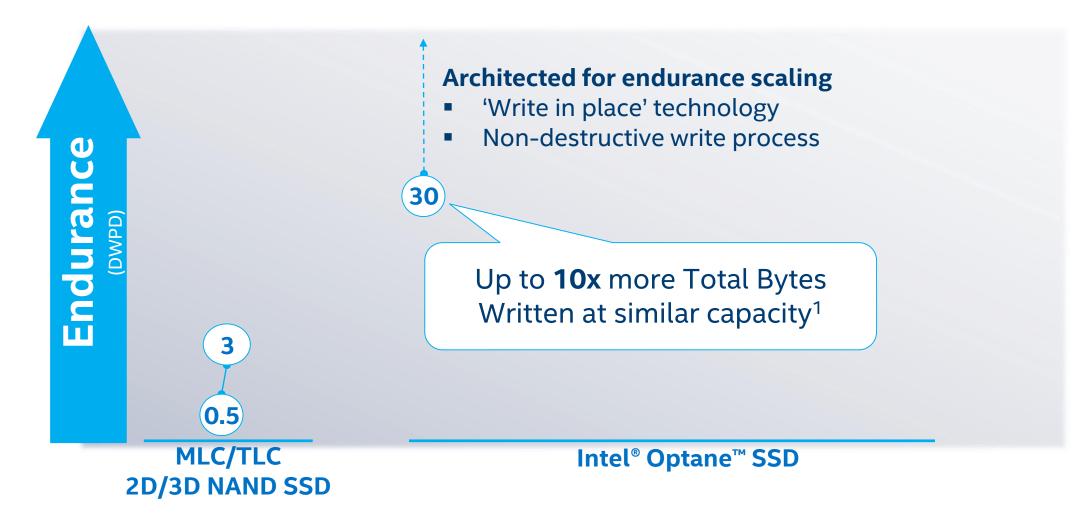
Responsive Under Load



^{1.} Benchmark results were obtained prior to implementation of recent software patches and firmware updates intended to address exploits referred to as "Spectre" and "Meltdown." Implementation of these updates may make these results inapplicable to your device or system. Responsiveness defined as average read latency measured at queue depth 1 during 4k random write workload. Measured using FIO 2.15. Common Configuration - Intel 2U Server System, OS CentOS 7.2, kernel 3.10.0-327.el7.x86_64, CPU 2 x Intel® Xeon® E5-2699 v4 @ 2.20GHz (22 cores), RAM 396GB DDR @ 2133MHz. Configuration – Intel® Optane™ SSD DC P4800X 375GB and Intel® SSD DC P3700 1600GB. Latency – Average read latency measured at QD1 during 4K Random Write operations using fio-2.15. Tests document performance of components on a particular test, in specific systems. Differences in hardware, software, or configuration will affect actual performance.



Ultra Endurance



^{1.} Comparing projected Intel® Optane™ SSD 750GB specifications to actual Intel® SSD DC P4600 1.6TB specifications. Total Bytes Written (TBW) calculated by multiplying specified or projected DWPD x specified or projected warranty duration x 365 days/year. Tests document performance of components on a particular test, in specific systems. Differences in hardware, software, or configuration will affect actual performance.



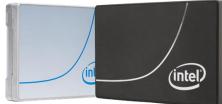
Intel® Data Center SSDs – Current Products

Use Case	Endurance	Interface	March 2018	
Intel® Optane™ Technology	Very High Endurance	PCIe*	Intel® Optane™ SSD DC P4800X; U.2 15mm: 375GB, 750GB AIC: 375GB, 750GB	
			Intel® Optane™ SSD DC P4800X with Intel® Memory Drive Technology; U.2 15mm: 375GB, 750GB AIC: 375GB, 750GB	
Server Performance	Mid	PCIe*	DC P4600; U.2 15mm: 1.6TB, 2TB, 3.2TB	
			DC P4600; AIC: 2TB, 4TB	
		SATA	DC S4600; 2.5": 240GB, 480GB, 960GB, 1.92TB	
	Standard -	PCIe*	DC P4510: U.2 15mm: 1TB, 2TB, 4TB, 8TB	
			<u>DC P4500</u> ; U.2 15mm: 1TB, 2TB, 4TB AIC: 4TB	
		SATA	DC S4500: 2.5": 240GB, 480GB, 960GB, 1.92TB, 3.84TB	
			DC S3520: M.2 80mm: 150GB, 240GB, 480GB, 760GB, 960GB	
Low Power	Standard	PCIe*	DC P4501; U.2 7mm: 500GB, 1TB, 2TB, 4TB	
Value Performance	Value -	PCIe*	DC P3100; M.2 80mm: 128GB, 256GB, 512GB, 1TB	
		SATA	DC S3110: M.2 80mm: 128GB, 256GB, 512GB	

^{*}Other names and brands may be claimed as the property of others.



HHHL (CEM3.0)



U.2 15mm



M.2 110mm



U.2 7mm



PCI Express* SSD Form Factor Evolution

M.2



M.2 initially designed for client and mobile use. Used in data center for boot or compute nodes, but lacks hot-plug support and requires carrier cards / heatsinks to manage thermals

U.2





U.2 2.5in x 15mm and 7mm supports hot-plug and serviceability, designed to share physical dimensions with HDDs for hybrid HDD/SSD server designs. Mainstream PCIe* SSD form factor

AIC





PCIe* low profile add-in-cards have broadest compatibility with the most mature ecosystem and compliance. Shares same form factor with network cards, graphic cards, etc.



Built for data center racks

High per drive, per server and per rack capacity
Improved manageability and serviceability
Efficient thermal design
Integrated enclosure, latch, LEDs

*Other names and brands may be claimed as the property of others.



AN SSD REVOLUTION.

"RULER" FORM FACTOR FOR INTEL SSDS.



Designed from the ground up to optimize rack efficiency, the new Ruler Form Factor delivers unparalleled Space-Efficient Capacity, Operationally- Efficient Design and Scalable Manageability.

Now available with the cloud-inspired Intel® SSD DC P4500 Series.

Optimized Storage for Data Center Racks.



Space Efficient Capacity



- Storage density optimized design delivers higher per drive capacity
- 1U optimized form factor delivers up to 32 drives per U for higher per server capacity

Operationally Efficient Design



- Up to **55% more thermally** efficient than 15mm U.2¹
- Consolidate racks to reduce opex
- System-based design approach enables more efficient solutions

Efficient Management a Scale

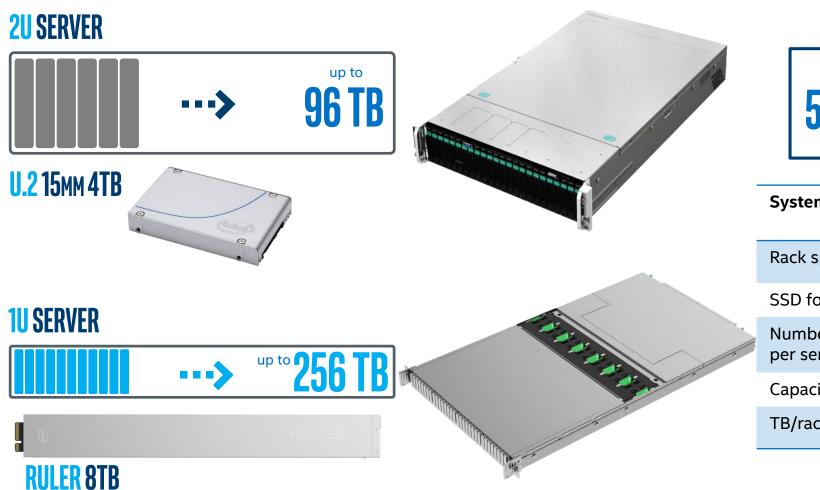


- Front loading and hot swappable
- Integrated power cycling enables remote, drive specific reboot
- Expanded and programmable LEDs enable indication of more device states

^{1.} Source – Intel. Results have been estimated or simulated using internal analysis or architecture simulation or modeling, and provided for informational purposes. Simulation includes "ruler" form factor for Intel® SSD DC P4500 4TB ruler, U.2 15mm Intel® SSD DC P4500, 3 drives in sheet metal representation of server, 12.5mm pitch for "ruler", 1000m elevation, limiting SSD on case temp of 70C or thermal throttling performance, whichever comes first. 5C guardband.



Optimized for Space Efficient Capacity per Server

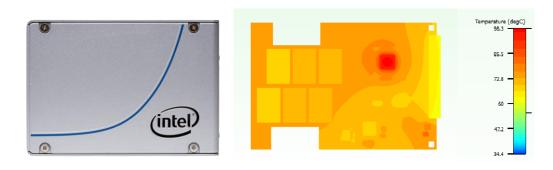


5.3x MORE TB PER RACK UNIT¹

System Type	Standard 2U Server	Intel® AF1000 Server
Rack space	2U	1U
SSD form factor	U.2 15mm	Intel ruler
Number of SSDs per server	24	32
Capacity per drive	4TB	8TB
TB/rack unit	48TB	256TB

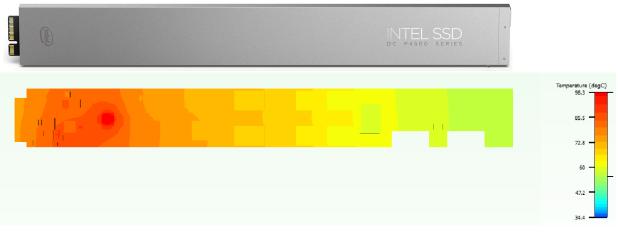
1. Source – Intel. Comparing maximum capacity per 1 rack unit of Intel® Server Board S2600WP Family, 24 U.2 bay option using 4TB U.2 15mm Intel® SSD DC P4500 to 8TB Intel® AF1000 Server design, 32 "ruler" drive bays using 8TB "ruler" form factor for Intel® SSD DC P4500.

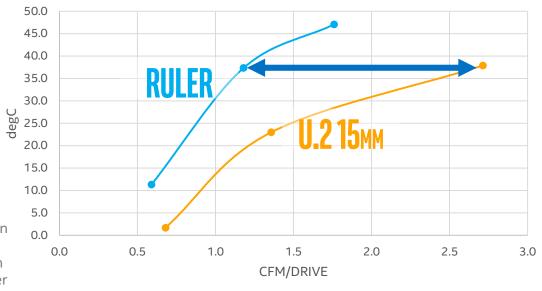
Thermal Efficient Design



UP TO 55% LESS AIRFLOW¹ vs U.2 15MM

 Source – Intel. Results have been estimated or simulated using internal analysis or architecture simulation or modeling, and provided for informational purposes. Simulation includes "ruler" form factor for Intel® SSD DC P4500 4TB ruler, U.2 15mm Intel® SSD DC P4500, 3 drives in sheet metal representation of server, 12.5mm pitch for "ruler", 1000m elevation, limiting SSD on case temp of 70C or thermal throttling performance, whichever comes first. 5C guardband.



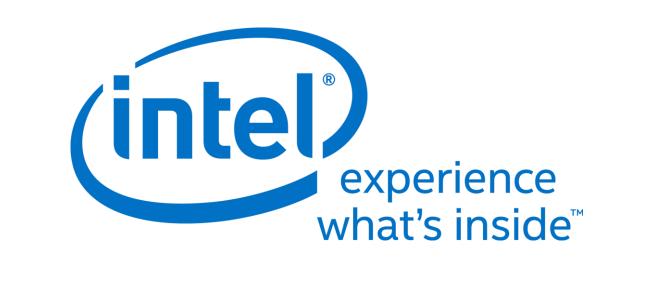






"Ruler" Form Factor for Intel SSDs Roadmap

- Move Ruler to compliance with EDSFF specifications
- Expand portfolio to include Intel® Optane™ SSDs in 2018



Notices & Disclaimers

Intel technologies' features and benefits depend on system configuration and may require enabled hardware, software or service activation. Performance varies depending on system configuration.

No computer system can be absolutely secure.

Tests document performance of components on a particular test, in specific systems. Differences in hardware, software, or configuration will affect actual performance. For more complete information about performance and benchmark results, visit http://www.intel.com/benchmarks.

Software and workloads used in performance tests may have been optimized for performance only on Intel microprocessors. Performance tests, such as SYSmark and MobileMark, are measured using specific computer systems, components, software, operations and functions. Any change to any of those factors may cause the results to vary. You should consult other information and performance tests to assist you in fully evaluating your contemplated purchases, including the performance of that product when combined with other products. For more complete information visit http://www.intel.com/benchmarks.

Benchmark results were obtained prior to implementation of recent software patches and firmware updates intended to address exploits referred to as "Spectre" and "Meltdown." Implementation of these updates may make these results inapplicable to your device or system.

Intel® Advanced Vector Extensions (Intel® AVX)* provides higher throughput to certain processor operations. Due to varying processor power characteristics, utilizing AVX instructions may cause a) some parts to operate at less than the rated frequency and b) some parts with Intel® Turbo Boost Technology 2.0 to not achieve any or maximum turbo frequencies. Performance varies depending on hardware, software, and system configuration and you can learn more at http://www.intel.com/go/turbo. Intel's compilers may or may not optimize to the same degree for non-Intel microprocessors for optimizations that are not unique to Intel microprocessors. These optimizations include SSE2, SSE3, and SSSE3 instruction sets and other optimizations. Intel does not guarantee the availability, functionality, or effectiveness of any optimization on microprocessors not manufactured by Intel. Microprocessor-dependent optimizations in this product are intended for use with Intel microprocessors. Certain optimizations not specific to Intel microarchitecture are reserved for Intel microprocessors. Please refer to the applicable product User and Reference Guides for more information regarding the specific instruction sets covered by this notice.

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